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DOCUMENT TITLE: PACKAGE LAND PATTERN, [F223B3FY+1] FC2QF

EFFECTIVE DATE: 05/11/2022

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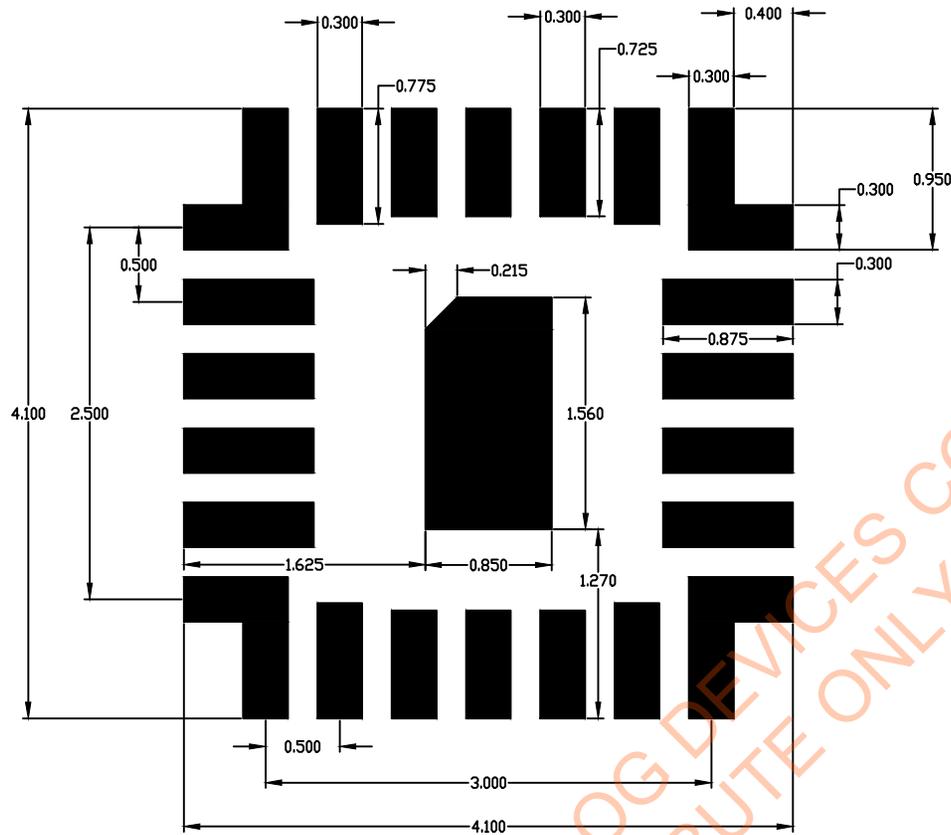
CHANGE NUMBER: 1160654

ORIGINATOR: Bernard Go

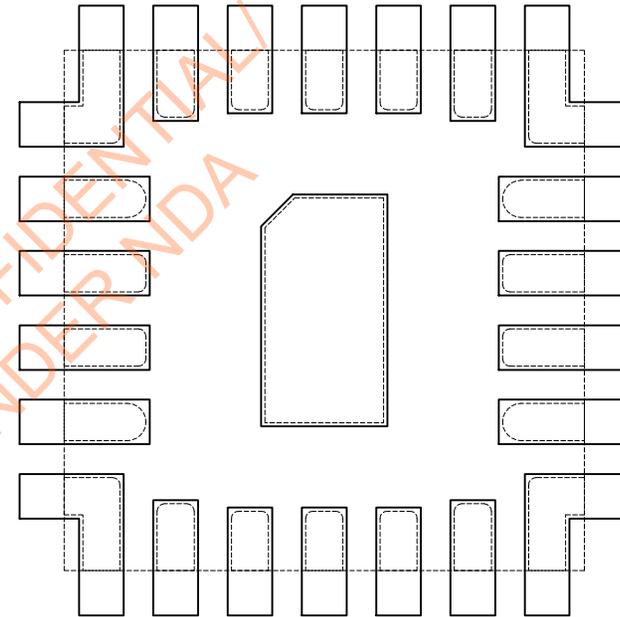
REASON FOR CHANGE:
INITIAL RELEASE

ANALOG DEVICES CONFIDENTIAL/
DISTRIBUTE ONLY UNDER NDA

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100663
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maxim-ic.com/support> for further questions.

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APPROVAL
YUANYUAN WEN

DOCUMENT CONTROL NO.
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